Welcome to ICEP-HBS 2026

On behalf of the Organizing Committee, we are pleased to welcome you to the 25th International Conference on Electronics Packaging, held in conjunction with the IEEE EPS Hybrid Bonding Symposium (ICEP-HBS2026). The event will take place at the International Conference Center Hiroshima from April 14 to 18, 2026.

Under the theme "Toward a Sustainable AI Computing Era," ICEP aims to collaborate with major international conferences worldwide to rapidly connect region-specific technologies with the global community, while providing a platform supporting the advancement of semiconductor packaging technologies.

Organized by the Japan Institute of Electronics Packaging (JIEP) and co-sponsored by IEEE EPS, IEEE EPS Japan Chapter, SMTA, and IMAPS, ICEP has evolved since its start as the International Microelectronics Conference (IMC) in 1980, adopting its current name in 2001.

We are proud to realize the first joint event with the IEEE EPS HBS in this milestone year marking the 25th anniversary of ICEP. The HBS special session will provide groundbreaking insights into bonding technologies and serve as the opening event of ICEP-HBS2026.

ICEP-HBS2026 is becoming a premier conference in electronics packaging, gathering leading experts from industry, academia, and research. Featuring over 280 oral and poster presentations—a record for ICEP—the conference provides a platform for global researchers and engineers to explore new challenges and future directions. Topics include advanced packaging, design, modeling, reliability, emerging technologies, high-speed wireless components, thermal management, interconnections, materials, optoelectronics, power electronics, and more. Long-term partners such as iNEMI, IMAPS, IMPACT, ISMP, and SMTA will present regional technology trends, alongside sessions from EPTC, ICEPT, and MEF.

We sincerely thank our sponsors, committee members, session chairs, authors, presenters, local organizers, and secretariats for their dedication. We hope you enjoy the engaging talks and fruitful discussions at ICEP-HBS2026 amidst the beautiful surroundings of Hiroshima City, a symbol of peace.

Sincerely,

Morikawa

Yasuhiro Morikawa, Ph.D
General Chair, ICEP-HBS2026